The Most Accurate Manual Scribing System Available

Handy Wafer Scriber

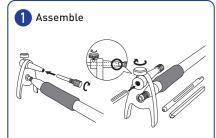


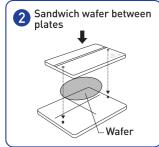
Features

- Suitable for scribing lnP, Glass, GaAs, Si, SiO2, Sapphire and SiC wafers up to 3 inches in diameter
- Predetermined scribing angle for optimal results
- Select tool. Secure wafer and scribe

- Two-part design with non-slip surface holds wafers firmly while scribing
- Unique pen design enables uniform scribing pressure

Instructions









TECDIA CO., LTD.

www.tecdia.com

Any information on this catalog may be modified without notice.

(2018.FEB) B-049-6



TECDIA Diamond Scribing Tools



